













ESD

TVS

TSS

MOV

GDT

PLED

NTTFS015N04C-MS

Product specification





Description

The NTTFS015N04C-MSuses advanced trench technology to provide excellent RDS(ON), low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

Features

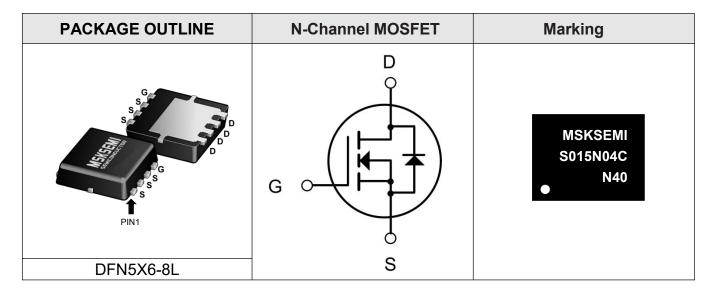
VDS = 40V ID = 50A

 $RDS(ON) < 14m\Omega$ VGS=10V

Application

- Battery protection
- Load switch
- Uninterruptible power supply

Reference News



Absolute Maximum Ratings (TC=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
Vds	Drain-Source Voltage	40	V
Vgs	Gate-Source Voltage	±20	V
ID @Tc=25°C	Continuous Drain Current, V gs @ 10V ¹	50	A
I⊳ @Tc=100°C	Continuous Drain Current, V cs @ 10V ¹	38	A
Ідм	Pulsed Drain Current ²	160	A
EAS	Single Pulse Avalanche Energy ³	50	mJ
Тята	Storage Temperature Range	-55 to 175	°C
TJ Operating Junction Temperature Range		-55 to 175	°C



Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	Rejc	1.76	°C /W	
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Electrical Characteristics (TA=25[°]Cunless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
Off Chara	cteristic				I	
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250µA	40	-	-	V
DSS	Zero Gate Voltage Drain Current	V _{DS} =40V, V _{GS} = 0V,	-	-	1	μA
lgss	Gate to Body Leakage Current	$V_{DS}=0V, V_{GS} = \pm 20V$	-	-	±100	μA
On Chara	cteristics	·				
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250µA	1.0	1.6	2.5	V
R _{DS(on)}	Static Drain-Source on-Resistance	V_{GS} =10V, I _D =30A	-	11	14	mΩ
g fs	Forward Transconductance	Vds=5V,Id=20A	30	-	-	S
Dynamic C	haracteristics ^(Note 4)		-		•	
Ciss	Input Capacitance		_	1540	_	pF
Coss	Output Capacitance	── V _{DS} =25V, V _{GS} =0V, f=1.0MHz	-	171	-	pF
Crss	Reverse Transfer Capacitance		-	115	-	pF
Switching	Characteristics(Note 4)		1	1	1	
t _{d(on)}	Turn-on Delay Time		-	5	-	ns
tr	Turn-on Rise Time	V _{DD} =20V, I _D =20A,RL=1Ω	-	24	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	38	-	ns
t _f	Turn-off Fall Time	V_{GS} =10V, R_{GEN} =3 Ω	-	12	-	ns
Qg	Total Gate Charge		-	24	-	nC
Qgs	Gate-Source Charge	── V _{DS} =30V, I _D =30A, ── V _{GS} =10V	-	5.9	-	nC
Q_{gd}	Gate-Drain Charge		-	3.6	-	nC
Drain-Sou	urce Diode Characteristics and	Maximum Ratings				
ls	Drain Forward Current ^(Note 2)		-	-	48	А
Vsd	Drain Forward Current ^(Note 3)	V _{GS} =0V, I _S =30A	-	-	1.2	V
trr	Reverse Recovery Time	TJ=25°C, IF=30A	-	9	-	ns
Qrr	Reverse Recovery Charge	di/dt=100A/µs ^(Note 3)	-	15	-	nC
ton	Forward Turn-On Time Intrinsic turn-on time is negligible(turn-on is dominated br LS+L			IS+ID		

Notes:

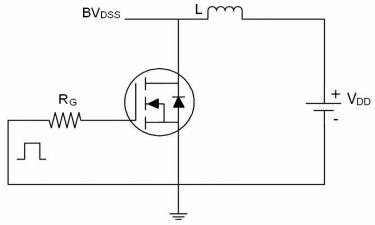
1. Repetitive Rating: Pulse width limited by maximum junction temperature.

- 2. Surface Mounted on FR4 Board, t≤10 sec.
- 3.Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production

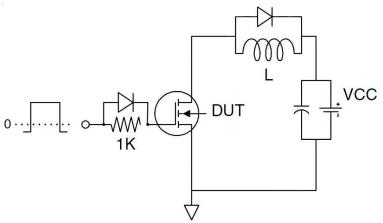
5. EAs condition: Tj=25 $^{\circ}$ C,VDD=30V,VG=10V,L=0.5mH,Rg=25 Ω



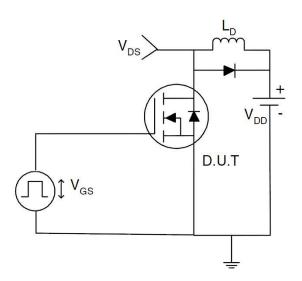
Test circuit 1) E_{AS} test Circuits



2) Gate charge test Circuit



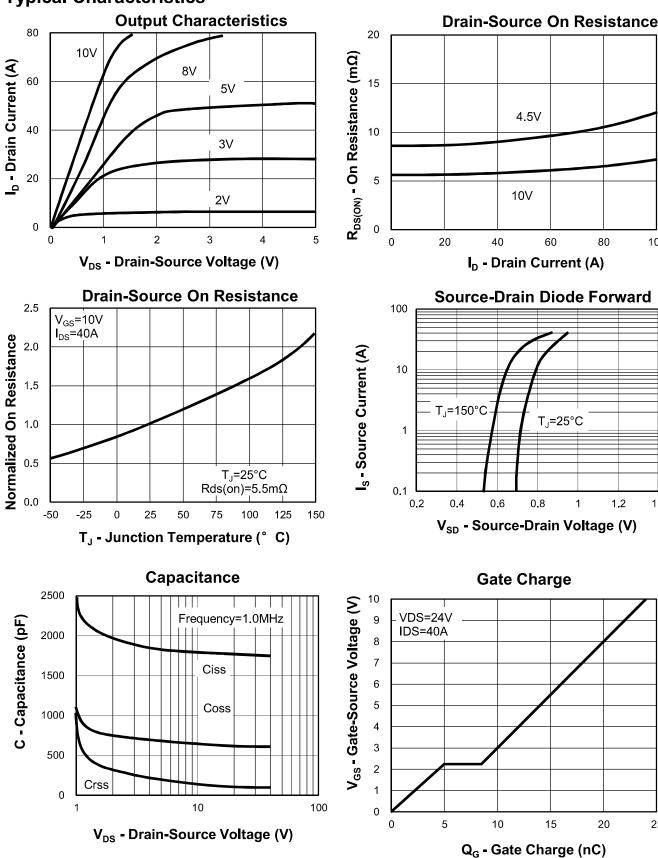
3) Switch Time Test Circuit





100

1.4

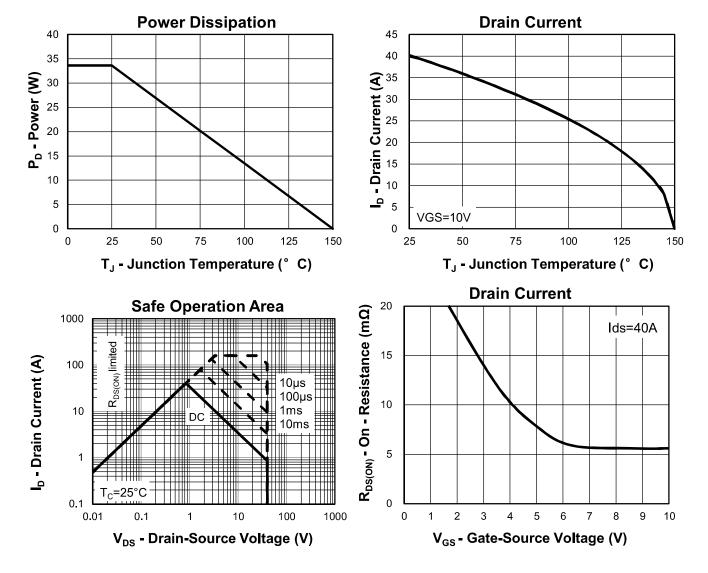


Typical Characteristics

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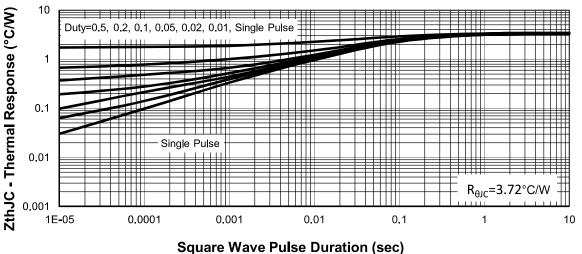
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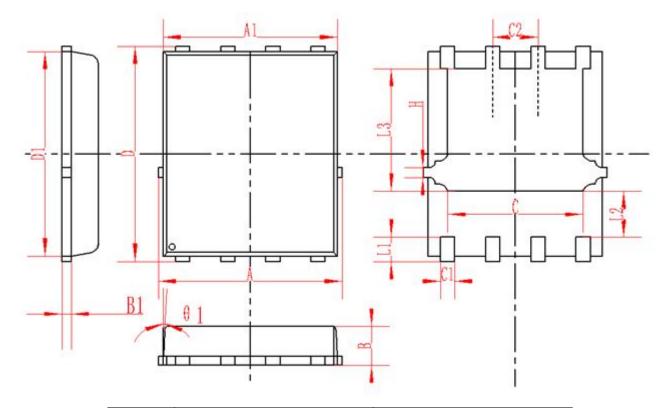
Typical Characteristics







DFN5X6-8L Package Information



			INCH			
STIVIDUL	MIN	NOM	MAX	MIN	NOM	MAX
А	4.95	5	5.05	0.195	0.197	0.199
A1	4.82	4.9	4.98	0.190	0.193	0.196
D	5.98	6	6.02	0.235	0.236	0.237
D1	5.67	5.75	5.83	0.223	0.226	0.230
В	0.9	0.95	1	0.035	0.037	0.039
B1		0.254REF			0.010REF	
С	3.95	4	4.05	0.156	0.157	0.159
C1	0.35	0.4	0.45	0.014	0.016	0.018
C2		1.27TYP			0.5TYP	
θ1	8.	10.	12。	8.	10.	12.
L1	0.63	0.64	0.65	0.025	0.025	0.026
L2	1.2	1.3	1.4	0.047	0.051	0.055
L3	3.415	3.42	3.425	0.134	0.135	0.135
Н	0.24	0.25	0.26	0.009	0.010	0.010

REEL SPECIFICATION

P/N	PKG	QTY
NTTFS015N04C-MS	DFN5X6-8L	5000

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